

Y-5335F/Y-5335FP

High Tg, Ultra Low loss, Halogen Free Laminate & Prepreg

产品特点

- Tg 220°C (DMA)
- Df 0.0050 (10G)
- 无卤, 阻燃等级 94V-0
- 厚度均匀性控制技术
- 适用无铅制程
- 优异的尺寸稳定性
- 低膨胀和优异的通孔可靠性

应用领域:

多层板, 服务器, 路由器, 基站及无线通讯等。

Key Features

- Tg 220°C (DMA)
- Df 0.0050 (10G)
- Halogen Free, Flammability Rating 94V-0
- Thickness uniformity control technology
- Lead free process compatible
- Excellent dimensional stability
- Low Z-axis CTE and excellent through hole reliability

Applications:

Multilayer PCB, Server, Router, Base station, RF/wireless Communication etc

General properties

Property	Item	IPC-TM-650	Test Condition	Units	Typical value
热性能 Thermal	玻璃化转变温度 Glass Transition Temperature	2.4.24.4	DMA	°C	220
		2.4.25	DSC	°C	200
	X,Y 轴方向膨胀系数 X,Y-CTE	2.4.24.5	TMA	ppm/°C	10~13
	Z 轴方向膨胀系数 Z axis-CTE	2.4.24	TMA, Before TG	ppm/°C	35
			TMA, After TG	ppm/°C	180
			50~260°C	%	1.8
			T288	min	≧ 120
			T300	min	≧ 120
288°C 热冲击 Thermal stress	2.6.8	288°C, solder dip	S	Pass	
热失重(weight loss 5%) Decomposition temperature	2.4.24.6	TGA	°C	400	
电性能 Electrical	体积电阻 Volume Resistivity	2.5.17.1	C-96/35/90	MΩ-cm	> 10 ⁸

	表面电阻 Surface Resistivity	2.5.17.1	C-96/35/90		MΩ	>10 ⁸
	耐电弧 Arc Resistance	2.5.1	A		S	120
	击穿电压 Dielectric Breakdown	2.5.6	A		KV	40
	电气强度 Electric Strength(thickness<0.5mm)	2.5.6.2	A		KV/mm	40
	介电常数 Permittivity (RC54%)	2.5.5.13	1GHz		/	3.75
			5GHz		/	3.73
			10GHz		/	3.72
	介电损耗 Loss Tangent (RC54%)	2.5.5.13	1GHz		/	0.0040
			5GHz		/	0.0045
			10GHz		/	0.0050
物理性能 Physical	弯曲强度 Flexural Strength	2.4.4	A	LW	MPa	460
				CW		420
	剥离强度 Peel Strength (1oz VLP)	2.4.8	288°C/10s		lb/inch	4.2
	阻燃等级 Flammability	UL94	UL94		/	V-0
	吸水率 Moisture Absorption	2.6.2.1	D-24/23		%	0.08

Specimen thickness: 1.50mm.

Test Method is according to IPC TM-650 or GB.

The data above is only for reference, and the actual data will have deviation, according to varieties of test equipment and method.